IEC 62769-1

Edition 3.0 2023-04

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Field device integration (FDI®) – Part 1: Overview

Intégration des appareils de terrain (FDI®) – Partie 1: Vue d'ensemble

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ICS 25.040.40; 35.100.05

ISBN 978-2-8322-6441-6

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FIELD DEVICE INTEGRATION (FDI®) –

Part 1: Overview

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IEC 62769-1 has been prepared by subcommittee 65E: Devices and integration in enterprise systems, of IEC technical committee 65: Industrial-process measurement, control and automation. It is an International Standard.

This third edition cancels and replaces the second edition published in 2021. This edition constitutes a technical revision.

This edition includes the following significant technical changes with respect to the previous edition:

a) added references to Part 6-100 and Part 6-200 (technology mapping for .NET and HTML5);
b) updated Subclause 8.3.1: major version, minor version and revision shall be written as two-digit numbers;
c) added reference to new Part 8 and FDI® OPC UA Server Facet.

The text of this International Standard is based on the following documents:

Draft	Report on voting
65E/854/CDV	65E/927/RVC

Full information on the voting for its approval can be found in the report on voting indicated in the above table.

The language used for the development of this International Standard is English.

This document was drafted in accordance with ISO/IEC Directives, Part 2, and developed in accordance with ISO/IEC Directives, Part 1 and ISO/IEC Directives, IEC Supplement, available at www.iec.ch/members_experts/refdocs. The main document types developed by IEC are described in greater detail at www.iec.ch/standardsdev/publications.

A list of all parts in the IEC 62769 series, published under the general title *Field device integration (FDI®)*, can be found on the IEC website.

The committee has decided that the contents of this document will remain unchanged until the stability date indicated on the IEC website under "http://webstore.iec.ch" in the data related to the specific document. At this date, the document will be

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FIELD DEVICE INTEGRATION (FDI®) –

Part 1: Overview

1 Scope

This part of IEC 62769 describes the concepts and overview of the Field Device Integration (FDI®[1]) specifications. The detailed motivation for the creation of this technology is also described (see 4.1). Reading this document is helpful to understand the other parts of this multi-part standard.

2 Normative references

The following documents are referred to in the text in such a way that some or all of their content constitutes requirements of this document. For dated references, only the edition cited applies. For undated references, the latest edition of the referenced document (including any amendments) applies.

IEC 61804 (all parts), *Devices and integration in enterprise systems − Function Blocks (FB) for process control and Electronic Device Description Language (EDDL)*

IEC 61804-3, *Devices and integration in enterprise systems − Function blocks (FB) for process control and electronic device description language (EDDL) − Part 3: EDDL syntax and semantics*

IEC 61804-4, *Devices and integration in enterprise systems − Function blocks (FB) for process control and electronic device description language (EDDL) − Part 4: EDD interpretation*

IEC 62453 (all parts), *Field device tool (FDT) interface specification*

IEC 62541 (all parts), *OPC Unified Architecture*

IEC TR 62541-1, *OPC Unified Architecture – Part 1: Overview and concepts*

IEC 62541-3, *OPC Unified Architecture – Part 3: Address Space Model*

IEC 62541-4, *OPC Unified Architecture – Part 4: Services*

IEC 62541-5, *OPC Unified Architecture – Part 5: Information Model*

IEC 62541-100, *OPC Unified Architecture – Part 100: Device Interface*

IEC 62769-2, *Field Device Integration (FDI®) – Part 2: Client*

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IEC 62769-3, *Field Device Integration (FDI®) – Part 3: Server*

IEC 62769-4:2023, *Field Device Integration (FDI®) – Part 4: FDI® Packages*

IEC 62769-5:2023, *Field Device Integration (FDI®) – Part 5: FDI® Information Model*

IEC 62769-6:2023, *Field Device Integration (FDI®) – Part 6: FDI® Technology Mappings*

IEC 62769-7, *Field Device Integration (FDI®) – Part 7: Communication Devices*

IEC 62769-8, *Field Device Integration (FDI®) – Part 8: EDDL to OPC-UA Mapping*

ISO/IEC 11578, *Information technology – Open Systems Interconnection – Remote Procedure Call (RPC)*

3 Terms, definitions, abbreviated terms and acronyms

3.1 Terms and definitions

For the purposes of this document, the terms and definitions given in IEC TR 62541-1, IEC 62541-3, IEC 62541-4, IEC 62541-5, IEC 62541-100 and the following apply.

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- IEC Electropedia: available at https://www.electropedia.org/
- ISO Online browsing platform: available at https://www.iso.org/obp

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3.1.1
Field Device Integration
FDI®
Device Integration and Device Management Technology, combining base concepts and technology aspects of the Electronic Device Description Language (EDDL) according to IEC 61804 series and Field Device Tool (FDT®) according to IEC 62453 series, as well as in IEC 62541-1 (OPC UA)

Note 1 to entry: The combination of those different proven technologies ensures a secure life-cycle and the ability to address all challenges of Device Integration and Device Management in a scalable manner.

3.1.2
Action
procedure that requires collaboration between an FDI® Client and an FDI® Server

3.1.3
Business Logic
descriptive element of an FDI® Package that specifies the device specific behaviour and/or mapping logic for a Nested Communication

3.1.4
Business Logic Interface
interface through which Business Logic is integrated with the Information Model

3.1.5
Communication Device
physical device that provides access to networks and devices

Note 1 to entry: Gateways and routers are examples of Communication Devices.

3.1.6
Device Access Services
set of services through which a User Interface Plug-in accesses the Information Model of an FDI® Server

3.1.7
Device Definition
required element of an FDI® Package that provides the core definition of a device

3.1.8
Device Instance
representation of a specific device in the Information Model of an FDI® Server

3.1.9
Device Tool
standalone application that contains both an FDI® Client and an FDI® Server

3.1.10
Device Type
representation of a type of device in the Information Model of an FDI® Server

3.1.11
FDI® Client
software component that uses the Information Model, interprets User Interface Descriptions, and hosts User Interface Plug-ins

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3.1.12
FDI® Communication Server
OPC UA server that is used by an FDI® Server to access non-native networks

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3.1.13
FDI® Package
collection of components that provide all the information necessary to integrate a type of device into a system

3.1.14
FDI® Server
software component that implements the Information Model, executes Business Logic, and communicates with device via Native Communication and/or Nested Communication

3.1.15
FDI® Technology Version
version number that identifies to a specific revision of the overall FDI® technology

3.1.16
Hosting Services
set of services through which a User Interface Plug-in interacts with an FDI® Client

3.1.17
Information Model
set of objects, variables, and methods exposed by an FDI® Server

3.1.18
Modular Device
device that is composed of one or more subdevices

3.1.19
Native Communication
communication with devices that are an integral part of the system

3.1.20
Nested Communication
communication with devices through a series of Communication Devices

3.1.21
User Interface Services
UI Services
set of services through which a User Interface Plug-in accesses the operating system

3.1.22
platform User Interface Services
platform UI Services
user interface services provided natively by the operating system

3.1.23
User Interface Description
UID
descriptive element of an FDI® Package that is used by an FDI® Client to render user interface

3.1.24
UID interpreter
User Interface Description interpreter
software component in an FDI® Client that renders User Interface Descriptions and invokes Actions

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3.1.25
User Interface Plug-in
UIP
executable element of an FDI® Package that is executed by an FDI® Client

3.1.26
UIP Services
User Interface Plug-in Services
set of services through which an FDI® Client interacts with a User Interface Plug-in

3.2 IEC TR 62541-1 terms (OPC UA)

For the purposes of this document, the following terms and definitions given in IEC TR 62541-1 apply.

AddressSpace
Attribute
Client
Method
Node
NodeClass
Notification
Object
ObjectType
Reference
ReferenceType

Server
Service Set
Session
Subscription
Variable

3.3 IEC 62541-3 (OPC UA) terms

For the purposes of this document, the following terms and definitions given in IEC 62541-3 (OPC UA) apply.

Aggregates
ArrayDimensions
AuditEvent
AuditUpdateMethodEvent
BrowseName
ByteString
DataType
DataVariable
Folder
HasComponent
HasProperty
HasSubType
HasTypeDefinition
ModellingRule
NodeId
Property
UserAccessLevel
UserExecutable
Value
ValueRank

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3.4 IEC 62541-4 (OPC UA) terms

For the purposes of this document, the following terms and definitions given in IEC 62541-4 (OPC UA) apply.

AddReferences
Browse
BrowseNext
Call
CreateSession
NodeManagement
Read
Request Header
Response Header
StatusCode
TranslateBrowsePathsToNodeIds

UserIdentityToken

Write

3.5 IEC 62541-5 (OPC UA) terms

For the purposes of this document, the following terms and definitions given in IEC 62541-5 apply.

BaseObjectType

PropertyType

3.6 IEC 62541-100 (OPC UA for Devices) terms

For the purposes of this document, the following terms and definitions given in IEC 62541-100 apply.

Block

Device

DeviceType

Parameter

3.7 Abbreviated terms and acronyms

DTM	Device Type Manager
EDD	Electronic Device Description
EDDL	Electronic Device Description Language
FB	Function blocks
FDI®	Field Device Integration
FDT®[2]	Field Device Tool (see IEC 62453 series)
GUI	Graphical User Interface
n/a	Not applicable
OPC	Open packaging conventions
OPC UA	OPC Unified Architecture (see IEC 62541 series)
PC	Personal computer
PNO	PROFIBUS Nutzerorganisation e. V. (is a regional organization of the PROFIBUS and PROFINET International consortium)
RPC	Remote Procedure Call
UI	User Interface
UID	User Interface Description
UIP	User Interface Plug-in
UUID	Universally unique identifier
XML	Extensible markup language
ZVEI	Zentralverband Elektrotechnik- und Elektronikindustrie e. V.

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3.8 Conventions

Capitalization of the first letter of words is used in the IEC 62769 series to emphasize an FDI® specific meaning. It is used for the following cases:

- defined terms,
- names of Services defined in IEC 62769-2,
- names of FDI® Package elements defined in IEC 62769-4,
- names of Information Model elements defined in IEC 62769-5,

EDD language elements are written with all letters in uppercase.

4 Background

4.1 Motivation

In today's automation systems, field devices from many different suppliers have to be integrated into the system, which results in additional effort for installation, version management and operation of these devices. This challenge is best met with an open and standardized device integration solution.

Two different device integration technologies exist: the Electronic Device Description Language (EDDL) according to IEC 61804 series and the Field Device Tool (FDT®) according to IEC 62453 series. While these technologies take different approaches to solve the problem, there is a lot of overlap between them. This has led to a situation where technologies compete with each other instead of complementing each other. As a result, system suppliers have taken their positions, device suppliers have had to double their efforts in order to support EDDL and FDT®, and the end users have become frustrated because they want the best of both technologies.

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For all parties involved, the ideal solution looks different. System suppliers want to achieve robustness while assuring a high level of technology and platform independence. Device suppliers want to support only one technology instead of two in order to reduce cost and effort, and they want to provide the optimal means for operating their devices. End users want to avoid false investments and therefore demand only one future-proof solution that offers all the advantages of the competing technologies.

4.2 Electronic Device Description Language (EDDL)

The Electronic Device Description Language (EDDL) is a language for describing the behaviour of field devices. It enables systems to configure, calibrate, troubleshoot, and operate a field device without any prior knowledge of the device.

Device descriptions written in EDDL describe the capabilities of the field device; it is up to the system to determine how to utilize these capabilities. These device descriptions enable systems to access all the data and properties of all devices, which simplifies the maintenance, support, and operation of the devices. It works well for small handheld applications and large integrated automation systems. It works well for embedded systems and systems running on commercial operating systems.

With EDDL, the device supplier can organize the device's data, properties, and procedures for access by the end user. This provides the system guidance in dynamically creating a user interface for the device. The capabilities of this user interface can vary significantly for different classes of devices, and it can be as simple or complex as the device being described.

In the early 1990s, the first version of EDDL was created and was used to describe HART field devices. In 1996, the EDDL was used to describe FOUNDATION Fieldbus devices. Then in 2000 it was used to describe PROFIBUS devices. All three versions of EDDL can trace their lineage back to the original HART version. Therefore, all three versions are largely the same, with some differences due to differences in the underlying communication protocols. EDDL was standardized first as part of IEC 61804-3 and IEC 61804-4 in March 2004.

4.3 Field Device Tool (FDT®)

FDT® is an interface specification that standardizes the interface between the device software and the systems. It provides independence from the communication protocol and establishes a clear boundary between the software provided by the device supplier and the software provided by the system supplier.

In FDT®, field devices are delivered with a device-specific software component called a Device Type Manager (DTM), which is only functional when used in conjunction with an FDT®-specific environment called a "frame application". A frame application interacts with a DTM through a set of standard FDT® interfaces.

A device supplier can develop a DTM for each of its devices, or it can develop a DTM for a group of devices. A DTM can be used to access Device Parameters, configure and operate the device, and diagnose problems. A DTM can range from a simple graphical user interface (GUI) for setting Device Parameters to a highly sophisticated application for performing complex calculations for diagnosis.

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DTMs can be nested in order to support Modular Devices. The nesting of DTMs also allows multi-level communication hierarchies to be supported. Devices routed through different bus protocols can be connected through standard interfaces. A device DTM just has to support its own communication protocol. Gateway DTMs that connect to the device DTM handle protocol transformation.

The FDT® specification supports a variety of bus protocols, for example: PROFIBUS®[3], HART®[4], FOUNDATION®[5] Fieldbus, INTERBUS®[6], AS-interface®[7], IO-Link®[2], DeviceNet®[8], and PROFINET® IO.

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